

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	IS&R	L1	30	(("3691007") or ("3743583") or ("3808576") or ("3857683") or ("3878006") or ("4808967") or ("4888574") or ("4892776") or ("5336391") or ("5689227") or ("5985124") or ("5049221")) .PN.	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 18:54			
2	IS&R	L2	10	(("3865702") or ("3743583") or ("5689227")) .PN.	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:03			
3	BRS	L3	9355	(428/615 or 428/621 or 428/626 or 428/650 or 428/652 or 428/675 or 428/680 or 428/681 or 428/686 or 428/931 or 428/935 or 205/125 or 205/271 or 205/272 or 205/273 or 205/920) .ccls.	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:05			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
4	BRS	L4	415	3 and (phosphoric ADJ acid or phosphorous ADJ acid or phosphorus ADJ acid or hypophosphorous ADJ acid or hypophosphorus ADJ acid)	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:08			
5	BRS	L5	151	4 and (nickel or ni) WITH (ion or ions or salt or salts or compound or compounds)	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:09			
6	BRS	L6	26	5 and (sulfamic ADJ acid or sulfamate)	US- PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:47			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	L7	4180	3 and (nickel or ni WITH layer WITH phosphorus)	US-PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:49			
8	BRS	L9	21	8 and (conductive WITH (base or substrate or layer))	US-PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 19:51			
9	BRS	L8	36	7 and resistance ADJ layer	US-PGPU B; USPA T; USOC R; EPO; JPO; DERW ENT; IBM TDB	2005/02/ 23 20:56			

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
1			US 2005003067 6 A1	20050210	97	Magnetoresistance effect element, magnetic head, magnetic head assembly, magnetic storage system	360/325	428/336; 428/591; 428/611; 428/686
2	X		US 2004017085 8 A1	20040902	15	Process for producing high temperature heat resisting carrier foil clad electrolytic copper foil and high temperature heat resisting carrier foil clad electrolytic copper foil obtained by the process	428/607	205/206; 205/291; 428/457; 428/626
3	X		US 2004014465 6 A1	20040729	6	Plating bath for forming thin resistance layer, method of formation of resistance layer, conductive base with resistance layer, and circuit board material with resistance layer	205/258	428/680
4	X		US 6783807 B2	20040831	7	Method for coating apparatuses and parts of apparatuses for the construction of chemical installations	427/437	427/307; 427/309; 427/438; 427/443.1; 428/565; 428/680

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
5	X		US 6610422 B1	20030826	52	Coated steel sheet and method for manufacturing the same	428/653	148/530; 148/531; 148/533; 427/398.1; ; 427/398.4; ; 427/398.5; ; 427/402; 427/405; 427/406; 427/409; 427/419.1; ; 427/419.2; ; 427/433; 427/436; 428/457; 428/472.1; ; 428/472.2; ; 428/621; 428/622; 428/623; 428/626; 428/628; 428/629; 428/632; 428/659; 428/933; 428/939
6	X		US 6482505 B1	20021119	20	Multi-layer texture layer	428/212	428/433; 428/612; 428/667; 428/680; 428/694SG; ; 428/694ST

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
7	X		US 6451448 B1	20020917	63	Surface treated metallic materials and manufacturing method thereof	428/612	257/E23.0 06; 257/E23.0 54; 257/E23.0 92; 428/601; 428/613; 428/620; 428/626; 428/674; 428/687
8	X		US 6329077 B1	20011211	6	Plate-shaped compression mold, process for producing the same and process for making laminate therewith	428/667	148/530; 156/580; 249/114.1 ; 249/187.1 ; 249/78; 427/123; 428/457; 428/545; 428/564; 428/577; 428/679; 428/680; 428/686; 428/687; 428/926; 428/940
9	X		US 6207298 B1	20010327	10	Connector surface-treated with a Sn-Ni alloy	428/646	257/677; 257/E23.0 54; 428/620; 428/628; 428/680; 439/887

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
10	X		US 6200672 B1	20010313	12	Surface-treated metal plate and metal surface treating fluid	428/328	106/14.12; 106/14.13; 106/14.14; 106/14.15; 106/14.21; 106/218; 106/287.29; 106/287.32; 106/287.35; 148/259; 148/260; 148/261; 148/273; 148/274; 148/275; 148/283; 428/469; 428/470; 428/621; 428/623; 428/659; 428/689

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
11	X		US 6045931 A	20000404	17	Magnetic recording medium comprising a cobalt-samarium magnetic alloy layer and method	428/694TS	204/192.1 ; 427/130; 427/131; 427/132; 427/294; 427/331; 427/399; 428/336; 428/457; 428/629; 428/632; 428/639; 428/650; 428/667; 428/694TP ; 428/900; 428/928
12	X		US 5976341 A	19991102	18	Process and apparatus for electrolytic deposition of metal layers	205/101	204/232; 204/237; 204/275.1 ; 205/125; 205/920
13	X		US 5770837 A	19980623	8	Metal plate for electromagnetic heating	219/621	126/390.1 ; 219/634; 220/573.1 ; 428/650; 428/658; 428/678
14	X		US 5569545 A	19961029	17	Copper clad laminate, multilayer printed circuit board and their processing method	428/626	428/462
15	X	X	US 5336391 A	19940809	6	Method for producing a circuit board material employing an improved electroplating bath	205/152	205/184; 205/215; 205/258; 205/920

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
16	X		US 5330850 A	19940719	17	Corrosion-resistant surface-coated steel sheet	428/623	428/626; 428/659
17	X		US 5304428 A	19940419	8	Copper foil for printed circuit boards	428/607	428/675; 428/935
18	X		US 5243320 A	19930907	17	Resistive metal layers and method for making same	338/308	338/309; 361/765; 428/607; 428/621
19	X		US 5061550 A	19911029	7	Multilayer material having a resistance layer formed on an electrically conductive layer and a multilayer board for a printed circuit board which has a resistance layer	428/209	205/125; 427/97.6; 428/409; 428/446; 428/457; 428/901
20	X		US 5034284 A	19910723	4	Thermal fatigue resistant coatings	428/680	416/241R; 427/405; 427/447; 427/455; 428/925; 428/937
21	X	X	US 4892776 A	19900109	7	Circuit board material and electroplating bath for the production thereof	428/209	205/125; 252/513; 428/656; 428/704; 428/901
22	X	X	US 4888574 A	19891219	7	Circuit board material and method of making	338/309	156/151; 205/152; 205/258; 205/920; 338/308
23	X		US 4814587 A	19890321	20	High power self-regulating heater	219/552	174/126.2; 219/229; 219/553; 219/667; 336/177; 336/73; 428/611; 428/615; 428/619

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
24	X		US 4732821 A	19880322	4	Nickel-based electrical contact	428/671	423/644; 428/680; 428/929
25	X		US 4592964 A	19860603	5	Wear-resistant coating	428/610	428/621; 428/627; 428/632
26	X		US 4368252 A	19830111	8	Printed circuit substrate with resistance elements	430/312	156/151; 174/260; 174/261; 205/125; 216/18; 216/19; 216/48; 29/831; 29/846; 338/307; 338/308; 427/102; 427/97.4; 430/313
27	X		US 4175010 A	19791120	4	Method of reinforcing a conductive base pattern by electroplating and device obtained by means of the method	428/621	204/192.1 5; 205/118; 205/123; 205/125; 205/260; 257/750
28	X		US 3957086 A	19760518	10	Corrosion resistant tubing	138/145	138/DIG.6 ; 428/675; 428/677; 428/680; 428/686; 428/926; 428/935; 428/941
29	X		US 3880603 A	19750429	14	Laminated magnetic material	428/620	148/527; 428/621; 428/630; 428/632; 428/680; 428/694TM

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
30	X		US 3869261 A	19750304	5	CORROSION-RESISTANT COMPOSITE COATING TO BE FORMED ON STEEL MATERIALS AND METHOD OF FORMING THE SAME	428/646	205/170; 205/176; 205/177; 205/182; 205/217; 205/95; 428/647; 428/658; 428/659; 428/674; 428/926; 428/935; 428/941
31	X		US 3786557 A	19740122	7	FABRICATION OF THIN FILM RESISTORS	29/620	205/125; 205/224; 257/532; 257/539; 257/E21.5 35
32	X		US 3489656 A	19700113	6	METHOD OF PRODUCING AN INTEGRATED CIRCUIT CONTAINING MULTILAYER TANTALUM COMPOUNDS	205/125	205/189; 216/16; 216/6; 257/533; 257/537; 427/96.8
33	X		US 3322655 A	19670530	8	Method of making terminated microwafers	205/125	205/188; 205/190; 216/13; 257/766; 29/597; 29/621; 427/96.8; 438/614; 438/652

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
34	X		US 2662957 A	19531215	13	Electrical resistor or semiconductor	338/2	106/157.2; 216/16; 216/20; 216/6; 219/553; 257/536; 29/620; 29/847; 327/579; 327/582; 338/255; 338/314; 338/327; 338/328; 361/765; 427/102; 427/103; 427/97.3; 428/596; 428/609; 428/614; 428/617; 428/620; 428/621; 428/686; 428/901; 428/931; 438/384; 438/478; 438/980
35	X		US 2491199 A	19491213	3	OCR SCANNED DOCUMENT	313/544	428/642; 428/681; 428/938
36	X		US 2446617 A	19480810	2	Method of producing electrically semiconducting coatings	427/102	257/E21.0 78; 427/101; 428/650; 438/104

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
1			US 2005003067 6 A1	20050210	97	Magnetoresistance effect element, magnetic head, magnetic head assembly, magnetic storage system	360/325	428/336; 428/591; 428/611; 428/686
2			US 2004014465 6 A1	20040729	6	Plating bath for forming thin resistance layer, method of formation of resistance layer, conductive base with resistance layer, and circuit board material with resistance layer	205/258	428/680
3			US 6482505 B1	20021119	20	Multi-layer texture layer	428/212	428/433; 428/612; 428/667; 428/680; 428/694SG; 428/694ST
4			US 6451448 B1	20020917	63	Surface treated metallic materials and manufacturing method thereof	428/612	257/E23.006; 257/E23.054; 257/E23.092; 428/601; 428/613; 428/620; 428/626; 428/674; 428/687
5			US 5770837 A	19980623	8	Metal plate for electromagnetic heating	219/621	126/390.1; 219/634; 220/573.1; 428/650; 428/658; 428/678

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
6			US 5569545 A	19961029	17	Copper clad laminate, multilayer printed circuit board and their processing method	428/626	428/462
7		X	US 5336391 A	19940809	6	Method for producing a circuit board material employing an improved electroplating bath	205/152	205/184; 205/215; 205/258; 205/920
8			US 5330850 A	19940719	17	Corrosion-resistant surface-coated steel sheet	428/623	428/626; 428/659
9			US 5243320 A	19930907	17	Resistive metal layers and method for making same	338/308	338/309; 361/765; 428/607; 428/621
10			US 5061550 A	19911029	7	Multilayer material having a resistance layer formed on an electrically conductive layer and a multilayer board for a printed circuit board which has a resistance layer	428/209	205/125; 427/97.6; 428/409; 428/446; 428/457; 428/901
11		X	US 4892776 A	19900109	7	Circuit board material and electroplating bath for the production thereof	428/209	205/125; 252/513; 428/656; 428/704; 428/901
12		X	US 4888574 A	19891219	7	Circuit board material and method of making	338/309	156/151; 205/152; 205/258; 205/920; 338/308

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
13			US 4814587 A	19890321	20	High power self-regulating heater	219/552	174/126.2; 219/229; 219/553; 219/667; 336/177; 336/73; 428/611; 428/615; 428/619
14			US 4368252 A	19830111	8	Printed circuit substrate with resistance elements	430/312	156/151; 174/260; 174/261; 205/125; 216/18; 216/19; 216/48; 29/831; 29/846; 338/307; 338/308; 427/102; 427/97.4; 430/313
15			US 4175010 A	19791120	4	Method of reinforcing a conductive base pattern by electroplating and device obtained by means of the method	428/621	204/192.1 5; 205/118; 205/123; 205/125; 205/260; 257/750
16			US 3880603 A	19750429	14	Laminated magnetic material	428/620	148/527; 428/621; 428/630; 428/632; 428/680; 428/694TM
17			US 3786557 A	19740122	7	FABRICATION OF THIN FILM RESISTORS	29/620	205/125; 205/224; 257/532; 257/539; 257/E21.5 35

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
18			US 3489656 A	19700113	6	METHOD OF PRODUCING AN INTEGRATED CIRCUIT CONTAINING MULTILAYER TANTALUM COMPOUNDS	205/125	205/189; 216/16; 216/6; 257/533; 257/537; 427/96.8
19			US 3322655 A	19670530	8	Method of making terminated microwafers	205/125	205/188; 205/190; 216/13; 257/766; 29/597; 29/621; 427/96.8; 438/614; 438/652
20			US 2662957 A	19531215	13	Electrical resistor or semiconductor	338/2	106/157.2; 216/16; 216/20; 216/6; 219/553; 257/536; 29/620; 29/847; 327/579; 327/582; 338/255; 338/314; 338/327; 338/328; 361/765; 427/102; 427/103; 427/97.3; 428/596; 428/609; 428/614; 428/617; 428/620; 428/621; 428/686; 428/901; 428/931; 438/384; 438/478; 438/980

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef
21			US 2446617 A	19480810	2	Method of producing electrically semiconducting coatings	427/102	257/E21.0 78; 427/101; 428/650; 438/104